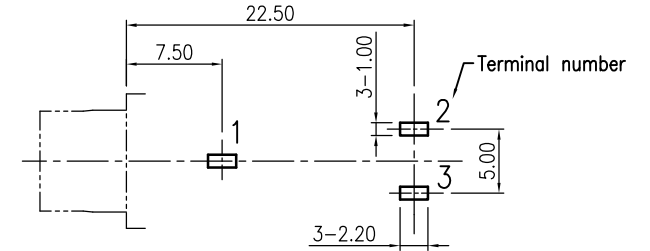
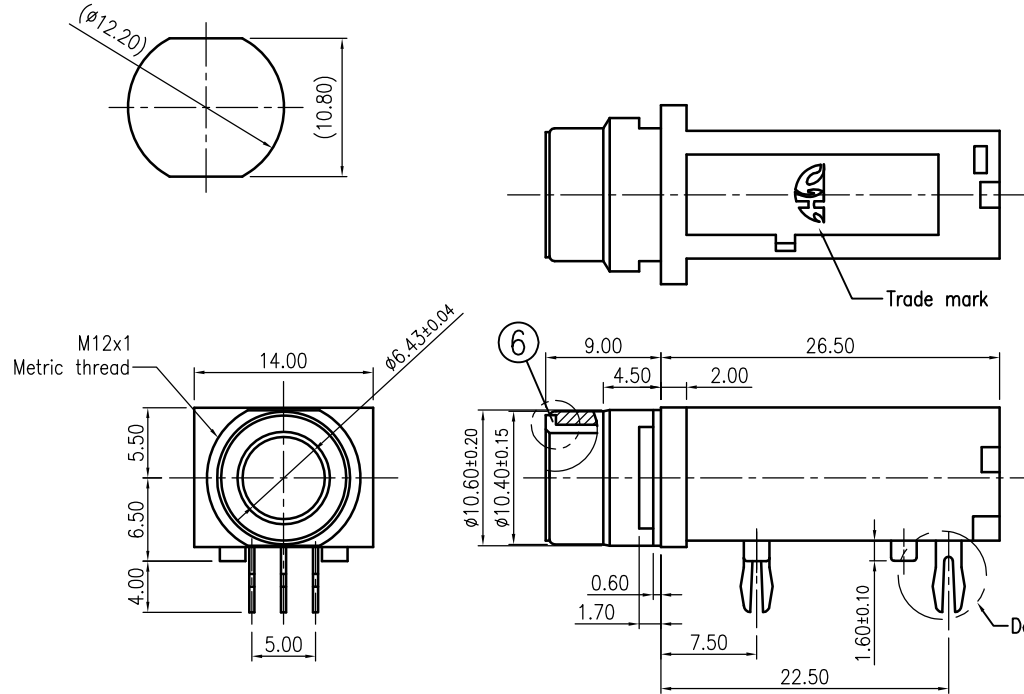
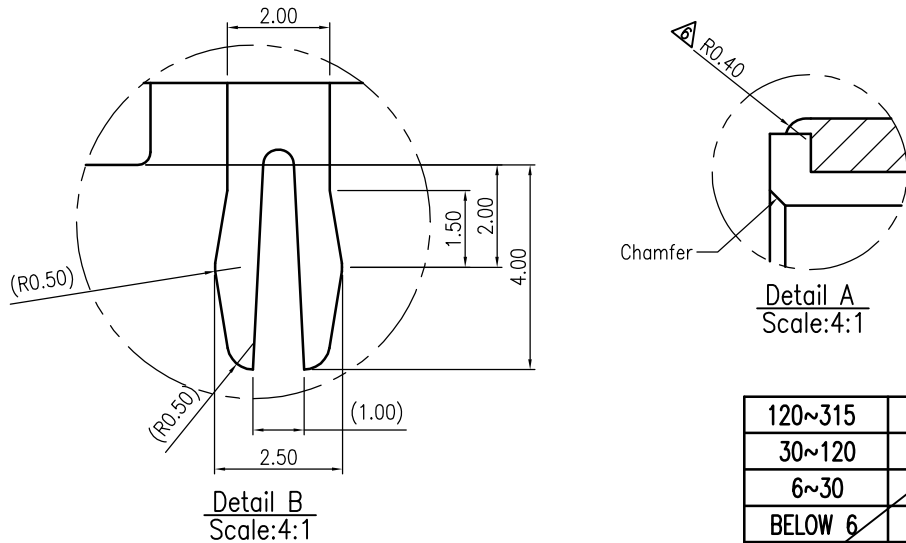
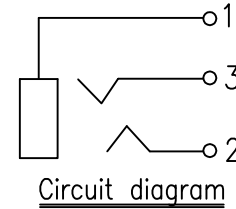


REVISIONS

LTR	DESCRIPTION	DATE	REV.	CHKD.	APVD.
△x1	更改外型尺寸,與實物相符	2008.06.12	楊志彬	關雄浪陸昌妹	林倫旋
△x1	To correct the material (ECR: C03110305)	2011.08.02	黃健璋	郭素玲	郭遠峰



PCB Layout Dimension (Tolerance: ±0.10)
(Recommend min. Dimension)(Bottom View)



△ 6	BUSHING	1	Brass
5	RING SPRING (3)	1	Copper Alloy t=0.30
4	TIP SPRING (2)	1	Copper Alloy t=0.40
3	EARTH SPRING (1)	1	Copper Alloy t=0.30
2	COVER	1	PBT+GF UL 94V-0
1	HOUSING	1	PBT+GF UL 94V-0

Please refer color and plating combination list.

LTR	PART NAME	Q'TY	MATERIAL	REMARK
120~315	±0.5	DWN	李阮龍	DATE 2008.05.29
30~120	±0.35	DSND	劉望全	DATE 2006.02.14
6~30	±0.22	CHKD	夏正雄	DATE 2008.05.29
BELOW 6	±0.16	APVD	郭遠峰	DATE 2008.05.29

NAME	PHONE JACK
CAT. NO.	HTJ-064-11D_
DWN.NO.	A-06411D
	1/1
	G

UNLESS OTHERWISE SPECIFIED, TOLERANCE ON DECIMAL: ±0.30 ANGLES: ±5°

KUNMING ELECTRONICS CO.,LTD.